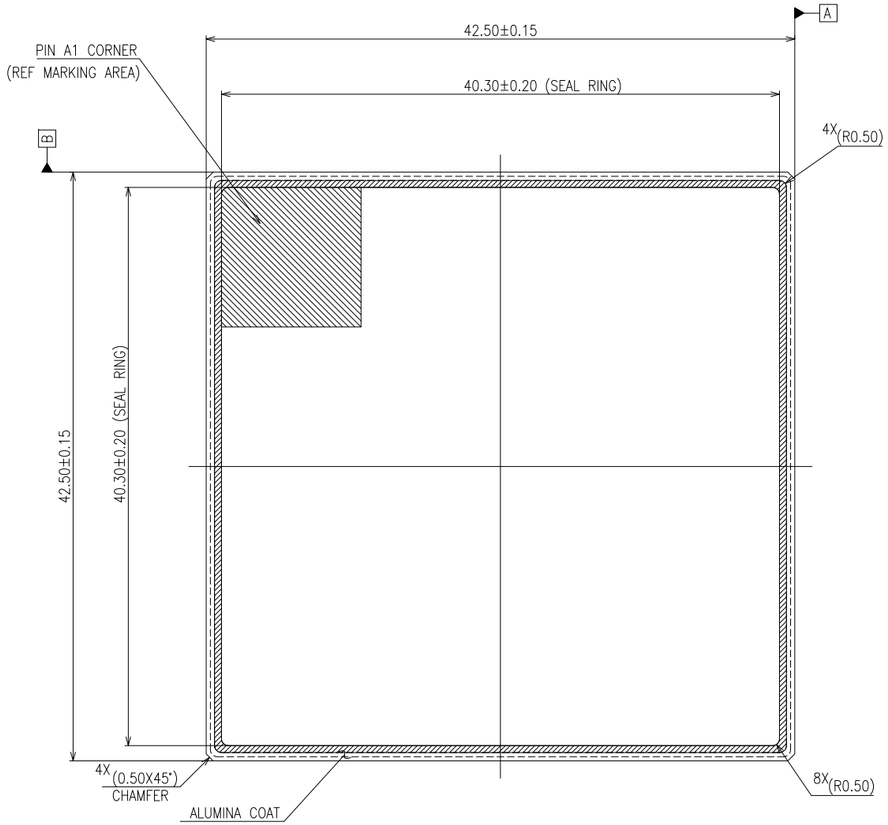
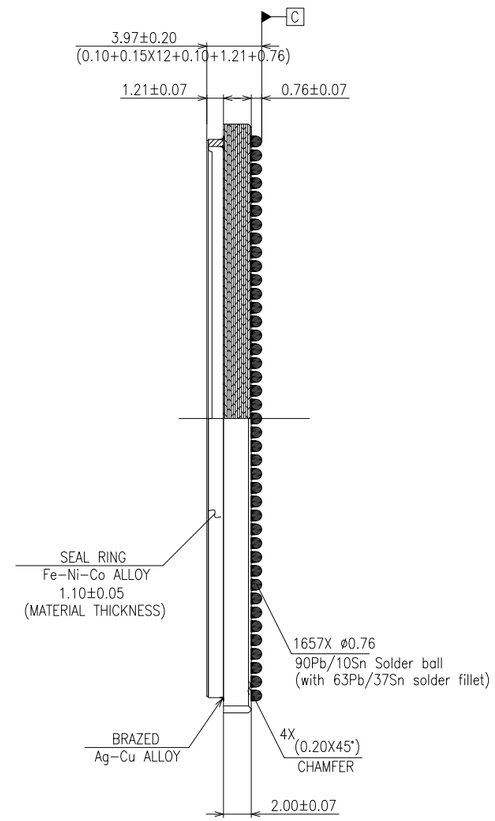
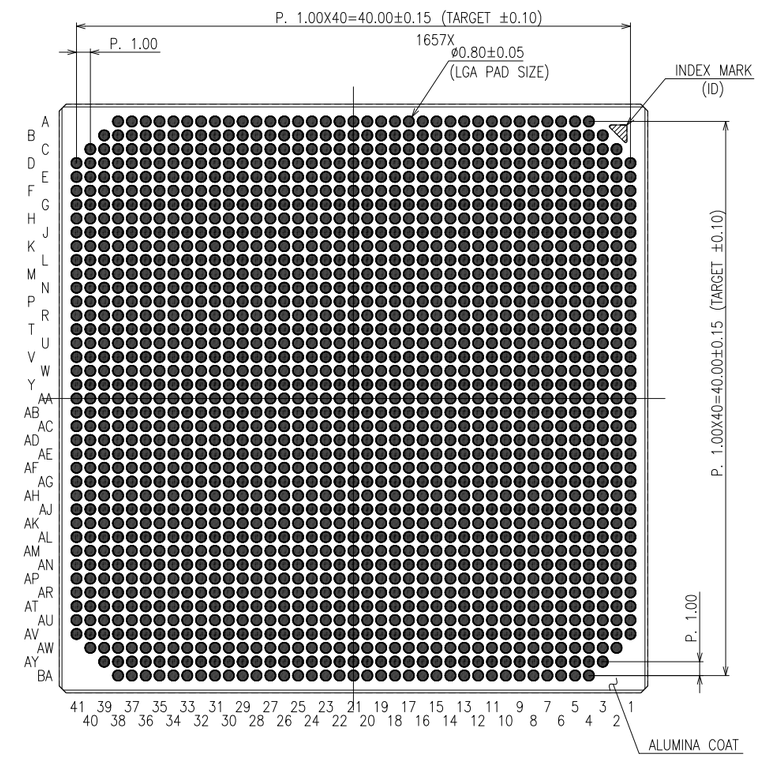
ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20150128	0	New Release	11/20/2014	Lijie Zhao







GENERAL TOLERANCE

DECIMAL	ANGULAR
±0.20	±1°

DIMENSIONS: Millimeters (mm)

PROJECTION	
APPROVALS	DATE
DRAWN	
CHECKED Erwin Q	11z/24/2014
ENG'R	
RELEASED	

Microsemi®

MICROSEMI CORPORATION, SOC GROUP
3850 N 1st St
San Jose, CA 95134

TITLE
CB1657, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 LAND PADS
FLIP CHIP, CERAMIC HIGH-TEMP SOLDER BALL GRID ARRAY, PACKAGE OUTLINE DRAWING

VENDOR NAME:	Microsemi DWG. NUMBER	REV
KYOCERA	1-21-111049	0
Heat Spreader Doc Number: N/A	VENDOR DWG. NUMBER: KD-YB4319	REV 0
	SCALE: NONE	SHEET 1 OF 1

1-06-13016 Rev. 2